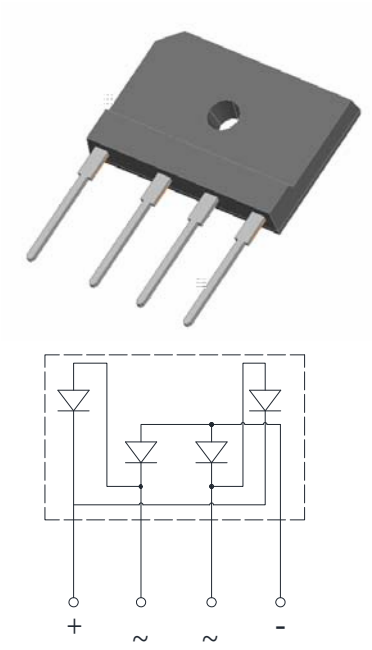
Low VF Bridge Rectifiers



Features

- UL recognition, file #E230084
- Glass passivated chip junction
- Thin single in-line package
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.

Mechanical Data

- **Package**: 6KBJ
  Molding compound meets UL 94 V-0 f ᵐ ᵀ Â ® ᵀ V- ȿ ᴀ pound
- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** As marked on body

■Maximum Ratings (Ta=25 Unless otherwise specified

PARAMETER		SYMBOL	UNIT	GBJL2506S
Device marking code				GBJL2506S
Maximum Repetitive Peak Reverse Voltage		VRRM	V	600
Maximum RMS Voltage		VRMS	V	420
Maximum DC blocking Voltage		VDC	V	600
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =105 ł	IO	A	25.0
	Without heatsink Ta =25 ł			3.5
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25 ł		IFSM	A	400
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25 ł				800
Current squared time @1ms≤t≤8.3ms Tj=25 ł , Rating of per diode		I²t	A²S	664
Storage temperature		Tstg	ł	-55 ~ +150
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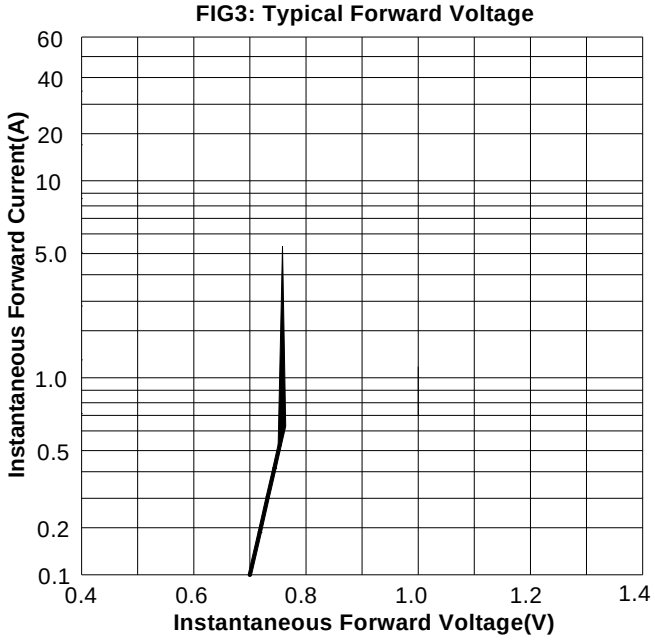
Dielectric strength @ Terminals to case, AC 1 minute		Vdis	KV	2.5
Mounting torque @Recommend torque 5kg cm		Tor	kg cm	8

■**Electrical Characteristics** T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	GBJL2506S
Maximum instantaneous forward voltage drop per diode				

FIG3: Typical Forward Voltage



■ Outline Dimensions

6KBJ		
Dim	Min	Max
A	29.7	30.3
B	19.7	20.3
C	17.0	18.0
D	4.8	5.8
E	3.8	4.2
F	7.3	7.7
G	9.8	10.2
H	0.9	1.1
I	2.0	2.4
J	2.3	2.7
K	3.4	3.8
L	4.4	4.8
M	10.8	11.2
N	3.1	3.7
O	3.1	3.4
P	0.6	0.8

Disclaimer

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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or τ ÿ ж ˜ he in ņ p of ʌ ɔ Mpre ņ a ɔ ʌ Ṅ dơ% tr "